

SMD CONTACT SPRINGS

FCB-11SX2030031B-YY-SMD

SMD contact springs are ideal for automatic assembly on printed circuit boards. They are soldered by the standard-reflow-soldering process.

The standard basic material used for SMD contact springs is copper beryllium (CuBe). However, other materials can also be supplied.

As standard, SMD springs are gold-plated (AU). They can be supplied in a wide range of dimensions and shapes.

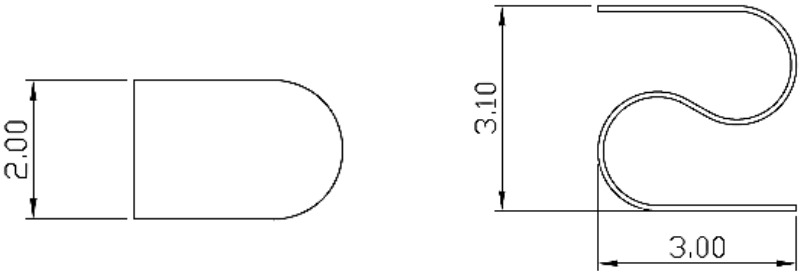
- Ideal for automatic assembly
- Standard basic material: CuBe
- Standard plating: AU
- Available in different dimensions and types
- Almost unlimited working life



PRODUCT SPECIFICATIONS

PROPERTY		VALUE / TOLERANCE
Thickness		0,08 mm
Width		2,0 mm ± 0,2
Length		3,0 mm ± 0,2
Height		3,1 mm ± 0,2
Basic material		Copper beryllium (CuBe)
Plating	Barrier layer NI Outer layer AU	1µm – 2µm 0,025µm – 0,075µm

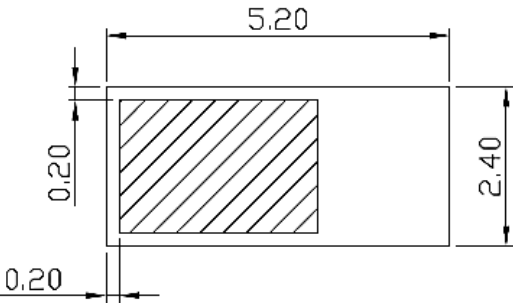
DIMENSIONS (mm)



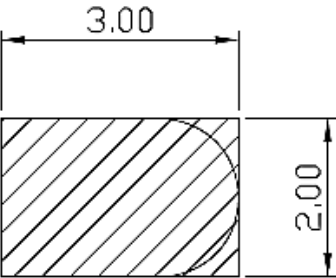
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RECOMMENDED RESERVED AREA ON THE PCB (mm)



RECOMMENDED PAD FOR THE PCB (mm)



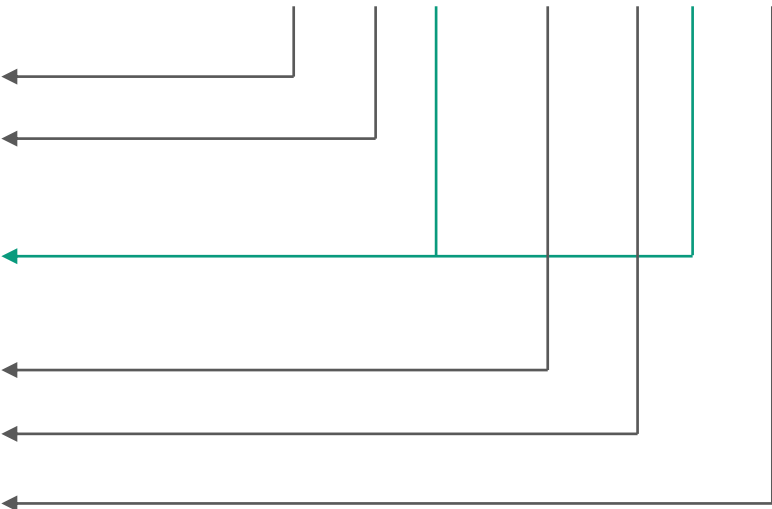
DISCLAIMER

This is only a recommendation based on information available to mtc at the time of printing. Actual land pattern can be significantly different due to various materials and processes used in PCB assembly. mtc makes no representation or warranty of performance based on the recommended land pattern.

BUILDING AN ITEM NUMBER

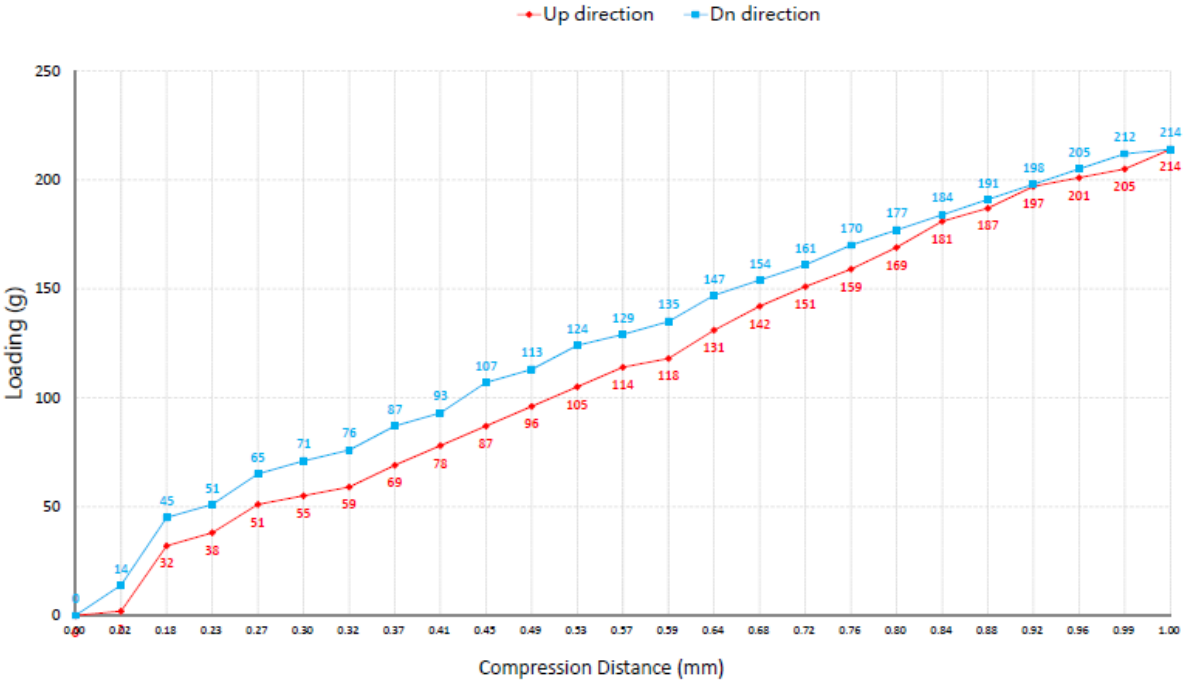
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Contact Spring	
Type number	
G/AU	Gold-plated
S/SN	Tin-plated
A/AG	Silver-plated
Dimensions	
Copper beryllium	
SMD type	



Standard options

FORCE DEFLECTION DIAGRAM*



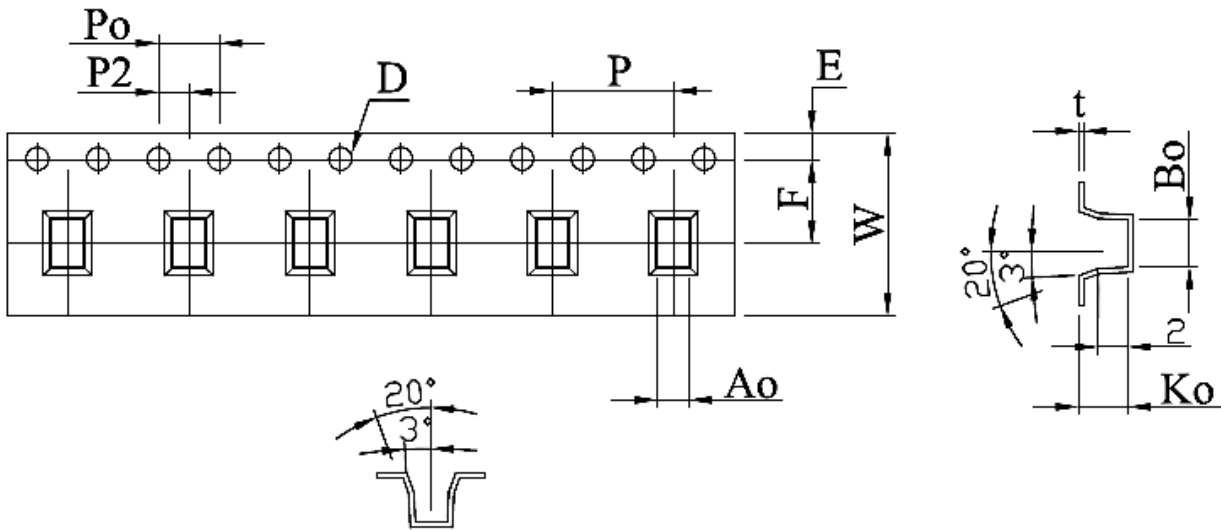
Total Compression Distance(mm)	1.00	
Displacement (mm)	Loading force(g) Down direction	Loading force(g) UP direction
0.00	0	0
0.02	14	2
0.18	45	32
0.23	51	38
0.27	65	51
0.30	71	55
0.32	76	59
0.37	87	69
0.41	93	78
0.45	107	87
0.49	113	96
0.53	124	105
0.57	129	114
0.59	135	118
0.64	147	131
0.68	154	142
0.72	161	151
0.76	170	159
0.80	177	169
0.84	184	181
0.88	191	187
0.92	198	197
0.96	205	201
0.99	212	205
1.00	214	214

NOTE | * Only valid for gold-plated version

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PACKING SPECIFICATION – TAPE AND REEL (mm)



	W	A ₀	B ₀	K ₀	P	F	E	D	P ₀	P ₂	T
	12,00	2,10	3,10	3,30	8,00	5,50	1,75	Ø 1,50	4,00	2,00	0,35
Tolerance	± 0,30	± 0,10	± 0,10	± 0,10	± 0,10	± 0,05	± 0,10	+ 0,10 - 0,00	± 0,10	± 0,05	± 0,05

- 10 sprocket hole pitch cumulative tolerance ± 0,20 mm.
- Carrier camber not to exceed 1 mm in 250 mm.
- A₀ and B₀ measured on a plane 0,3 mm above the bottom of the pocket.
- K₀ measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
- All dimensions meet EIA-481-B requirements.
- Material: Clear non anti-static polystyrene.
- Component load per 13" reel: 2.300 pcs (before 20 after 50 pcs).

Modifications and errors excepted. The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assume legal responsibility. Users should undertake sufficient verifications and testings to determine the suitability for their own particular purpose of any information or products referred to herein.